RELIABILITY REPORT

FOR

MAX8857AETL+

PLASTIC ENCAPSULATED DEVICES

July 1, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX8857AETL+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX8857A PMIC provides a complete power-supply solution for digital still cameras (DSCs) and digital video cameras (DVCs). The MAX8857A improves performance, component count, and board space utilization compared to currently available solutions for 2 AA cell and dual-battery designs. On-chip power MOSFETs provide up to 95% efficiency for critical power supplies. The CCD inverter can operate directly from 2 AA/NiMH batteries without the use of any additional external components.

- Step-up synchronous-rectified DC-DC converter (SU). The MAX8857A is bootstrapped from VSU.
- MAIN synchronous-rectified step-up DC-DC converter (M) with active discharge for DSP I/O supply voltage.
- SDZ synchronous-rectified step-down DC-DC converter (Z) for DSP DDR supply voltage.
- Low-voltage (down to 1V) synchronous-rectified step-down DC-DC converter (SD) for DSP core supply voltage.
- Step-up DC-DC converter with current regulation and PWM dimming control (LEDBST) for up to 6 series white LEDs (WLED).
- High-voltage step-up DC-DC converter (CCDBST) for CCD imagers or positive LCD bias supplies.
- Transformerless inverting DC-DC converter (CCDINV) for CCD imagers or negative LCD bias supplies. **This converter can connect directly to 2 AA batteries.** The MAX8857A has an independent/simultaneous power-on sequence of the CCDBST and CCDINV converters. For a preset power-on sequence of CCDBST before CCDINV, contact the factory. The MAX8857A is available in a 5mm x 5mm, 40-pin thin QFN package and operates over the -40°C to +85°C extended temperature range.

II. Manufacturing Information

A. Description/Function:	Smallest, All-Internal MOSFET, 7-Channel 2 AA DSC PMIC
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	California, Texas or Japan
E. Assembly Location:	Thailand
F. Date of Initial Production:	October 27, 2007

III. Packaging Information

A. Package Type:	40-pin TQFN 5x5
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2838
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	45°C/W
K. Single Layer Theta Jc:	1.7°C/W
L. Multi Layer Theta Ja:	28°C/W
M. Multi Layer Theta Jc:	1.7°C/W

IV. Die Information

A. Dimensions:	140 X 110 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Al/0.5%Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{\text{various} \times 4340 \times 461 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 0.87 \times 10^{-9}$

λ = 0.87 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S4 Process results in a FIT Rate of 0.28 @ 25C and 4.85 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PQ08 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX8857AETL+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	461	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data